

562/564 Series

Circuit Board Mount Blocks for TE5/TR5 Type Fuses



562 Series Holder

564 Series Holder

Additional Information



Resources
562 Series



Accessories
562 Series



Samples
562 Series



Resources
564 Series



Accessories
564 Series



Samples
564 Series

Product Characteristics

| | 562 Series | 564 Series |
|------------------------|--|---|
| Compatible Fuses | TR5/TE5 | |
| Materials | Block: Black Thermoplastic, UL94 V-0 PET Terminals: Copper alloy; solderable tinned | |
| Electrical Data (23°C) | Rated Voltage: 250V Max. Current/Power: 6.3A/1.6W | |
| Mounting | PC Board, 5.08mm pin spacing | PC Board, 5.08mm pad spacing |
| Minimum Cross Section | Conducting path - 0.1mm ² | Conducting path - 0.1mm ² |
| Unit Weight | 0.12g | 0.44g |
| Ambient Temperature | - 40°C to + 85°C | |

Ordering Information

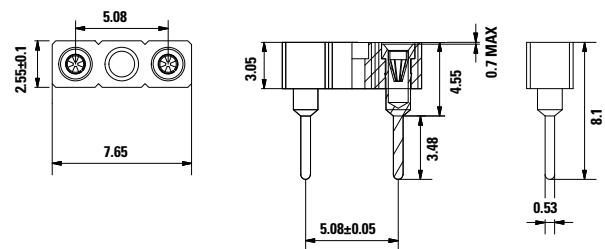
| Ordering Number | Circuit Board Mounting | Packaging |
|-----------------|------------------------|-------------------|
| 56200001009 | Thru-Hole | 1000 (Bulk pack) |
| 56400001009 | Surface Mount | 1500 (Tape /Reel) |

Agency Approvals

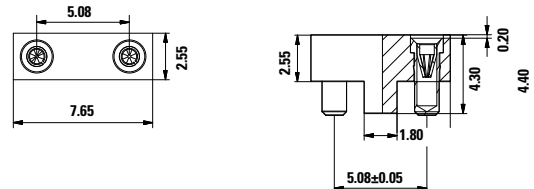
| Agency | Agency File Number | |
|--------|--------------------|------------|
| | 562 Series | 564 Series |
| | E14721 | E14721 |

Dimensions units in mm

562 Series Holder



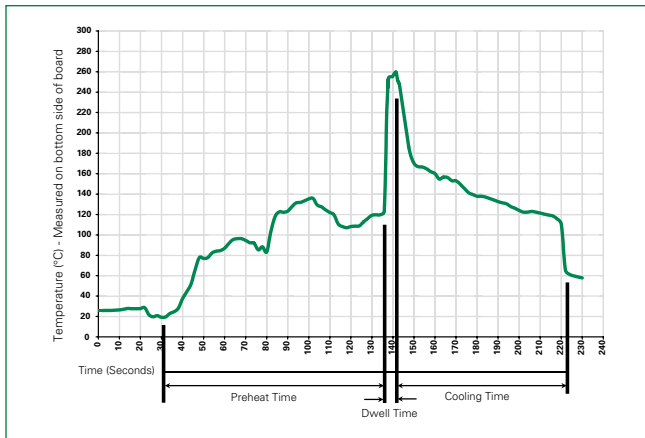
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Soldering Parameters - Wave Soldering



Recommended Process Parameters:

| Wave Parameter | Lead-Free Recommendation |
|--|-----------------------------------|
| Preheat: (Depends on Flux Activation Temperature) | (Typical Industry Recommendation) |
| Temperature Minimum: | 100°C |
| Temperature Maximum: | 150°C |
| Preheat Time: | 60-180 seconds |
| Solder Pot Temperature: | 260°C Maximum |
| Solder Dwell Time: | 2-5 seconds |

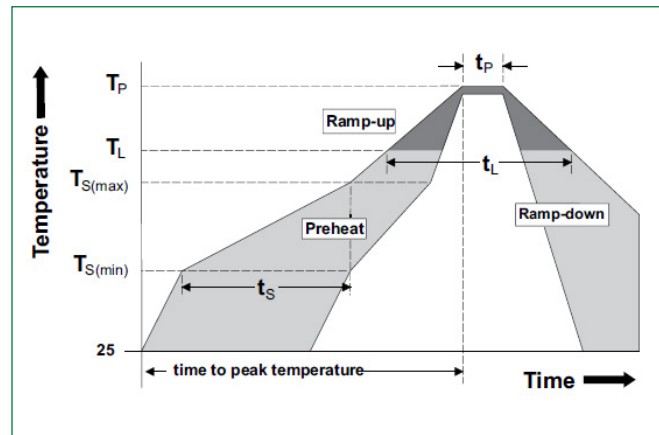
Recommended Hand-Solder Parameters:

Solder Iron Temperature: 350°C +/- 5°C
Heating time: 5 seconds max

Note: These devices are not recommended for IR and Convection Reflow process

Soldering Parameters - Reflow Soldering

| | | |
|--|------------------------------------|------------------|
| Reflow Condition | Pb - Free assembly | |
| Number of allowed reflow cycles | 3 | |
| Pre Heat | -Temperature Min ($T_{s(min)}$) | 150°C |
| | -Temperature Max ($T_{s(max)}$) | 200°C |
| | -Time (Min to Max) (t_p) | 60 - 120 Secs. |
| Average ramp up rate (Liquidus Temp (T_L) to peak) | 5°C/second max. | |
| $T_{s(max)}$ to T_L - Ramp-up Rate | 5°C/second max. | |
| Reflow | - Temperature (T_L) (Liquidus) | 217°C |
| | -Temperature (t_l) | 60 - 150 seconds |
| Peak Temperature (T_p) | 240 +/- 5 °C | |
| Time within 50C of actual peak Temperature (t_p) | 30 secs. max. | |
| Ramp-down Rate | 5°C/second max. | |
| Time 25°C to peak Temperature (T_p) | 8 minutes max. | |
| Do not exceed | 245°C | |



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